

MJ11015 (PNP); MJ11012, MJ11016 (NPN)

MJ11016 is a Preferred Device

High-Current Complementary Silicon Transistors

... for use as output devices in complementary general purpose amplifier applications.

- High DC Current Gain –
 $h_{FE} = 1000$ (Min) @ $I_C = 20$ Adc
- Monolithic Construction with Built-in Base Emitter Shunt Resistor
- Junction Temperature to $+200^\circ\text{C}$

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage MJ11012 MJ11015/6	V_{CEO}	60 120	Vdc
Collector-Base Voltage MJ11012 MJ11015/6	V_{CB}	60 120	Vdc
Emitter-Base Voltage	V_{EB}	5	Vdc
Collector Current	I_C	30	Adc
Base Current	I_B	1	Adc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C @ $T_C = 100^\circ\text{C}$	P_D	200 1.15	W W/ $^\circ\text{C}$
Operating Storage Junction Temperature Range	T_J, T_{stg}	-55 to +200	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.87	$^\circ\text{C}/\text{W}$
Maximum Lead Temperature for Soldering Purposes for ≤ 10 Seconds	T_L	275	$^\circ\text{C}$

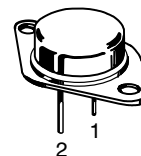
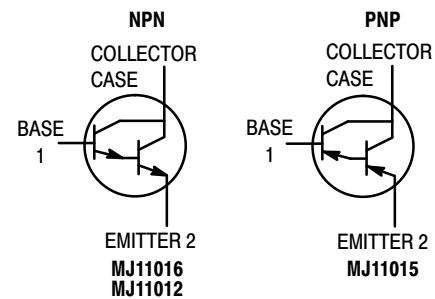
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



ON Semiconductor®

<http://onsemi.com>

30 AMPERE DARLINGTON POWER TRANSISTORS COMPLEMENTARY SILICON 60 – 120 VOLTS, 200 WATTS



TO-204AA (TO-3)
CASE 1-07
STYLE 1

MARKING DIAGRAM



MJ1101x = Device Code
x = 2, 5 or 6
G = Pb-Free Package
A = Location Code
YY = Year
WW = Work Week
MEX = Country of Origin

ORDERING INFORMATION

Device	Package	Shipping
MJ11012	TO-3	100 Units/Tray
MJ11012G	TO-3 (Pb-Free)	100 Units/Tray
MJ11015	TO-3	100 Units/Tray
MJ11015G	TO-3 (Pb-Free)	100 Units/Tray
MJ11016	TO-3	100 Units/Tray
MJ11016G	TO-3 (Pb-Free)	100 Units/Tray

Preferred devices are recommended choices for future use and best overall value.

MJ11015 (PNP); MJ11012, MJ11016 (NPN)

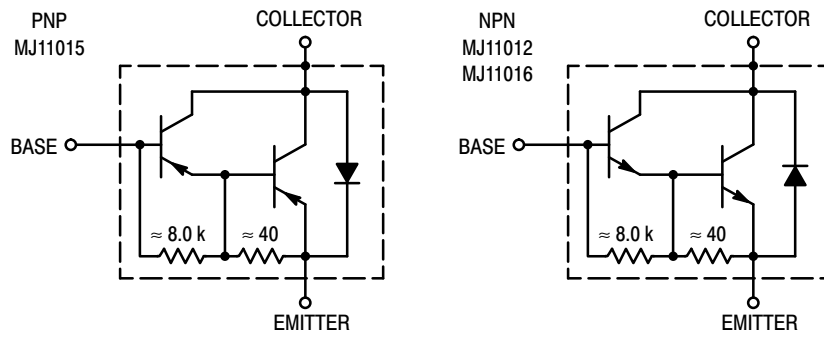


Figure 1. Darlington Circuit Schematic

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted.)

Characteristics	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage(1) ($I_C = 100\text{ mA dc}$, $I_B = 0$)	$V_{(BR)CEO}$	60 120	– –	Vdc
Collector–Emitter Leakage Current ($V_{CE} = 60\text{ Vdc}$, $R_{BE} = 1\text{ k ohm}$) ($V_{CE} = 120\text{ Vdc}$, $R_{BE} = 1\text{ k ohm}$) ($V_{CE} = 60\text{ Vdc}$, $R_{BE} = 1\text{ k ohm}$, $T_C = 150^\circ\text{C}$) ($V_{CE} = 120\text{ Vdc}$, $R_{BE} = 1\text{ k ohm}$, $T_C = 150^\circ\text{C}$)	I_{CER}	– – – –	1 1 5 5	mAdc
Emitter Cutoff Current ($V_{BE} = 5\text{ Vdc}$, $I_C = 0$)	I_{EBO}	–	5	mAdc
Collector–Emitter Leakage Current ($V_{CE} = 50\text{ Vdc}$, $I_B = 0$)	I_{CEO}	–	1	mAdc
ON CHARACTERISTICS(1)				
DC Current Gain ($I_C = 20\text{ Adc}$, $V_{CE} = 5\text{ Vdc}$) ($I_C = 30\text{ Adc}$, $V_{CE} = 5\text{ Vdc}$)	h_{FE}	1000 200	– –	–
Collector–Emitter Saturation Voltage ($I_C = 20\text{ Adc}$, $I_B = 200\text{ mAdc}$) ($I_C = 30\text{ Adc}$, $I_B = 300\text{ mAdc}$)	$V_{CE(sat)}$	– –	3 4	Vdc
Base–Emitter Saturation Voltage ($I_C = 20\text{ A}$, $I_B = 200\text{ mAdc}$) ($I_C = 30\text{ A}$, $I_B = 300\text{ mAdc}$)	$V_{BE(sat)}$	– –	3.5 5	Vdc
DYNAMIC CHARACTERISTICS				
Current–Gain Bandwidth Product ($I_C = 10\text{ A}$, $V_{CE} = 3\text{ Vdc}$, $f = 1\text{ MHz}$)	h_{fe}	4	–	MHz

(1) Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

MJ11015 (PNP); MJ11012, MJ11016 (NPN)

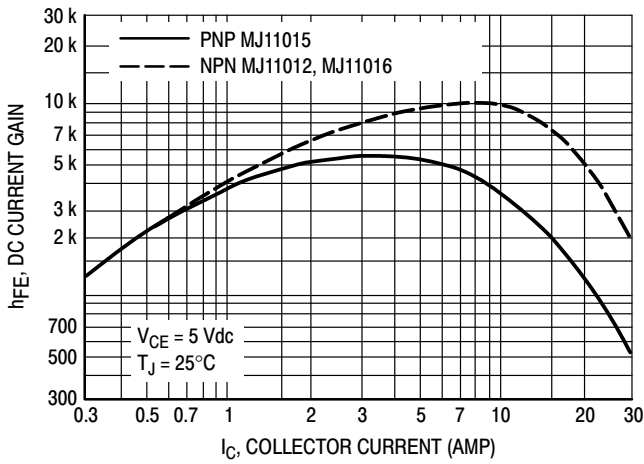


Figure 2. DC Current Gain (1)

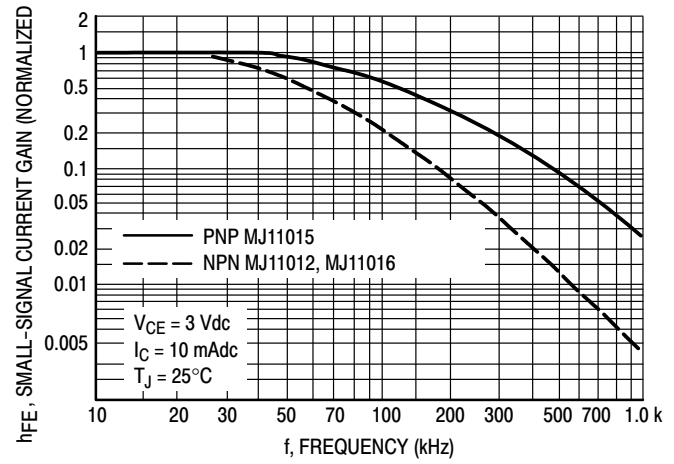


Figure 3. Small-Signal Current Gain

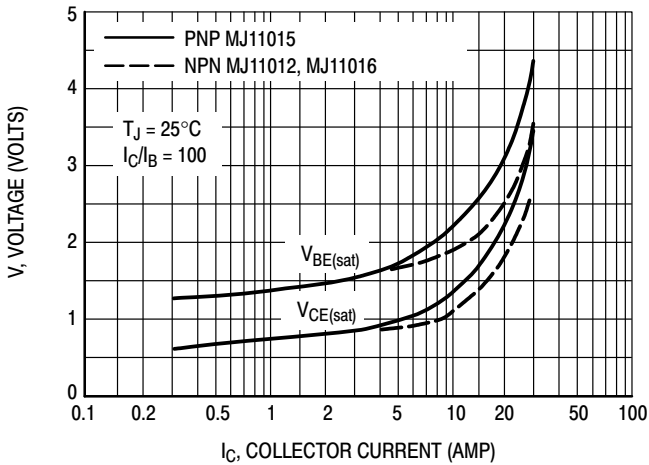


Figure 4. "On" Voltages (1)

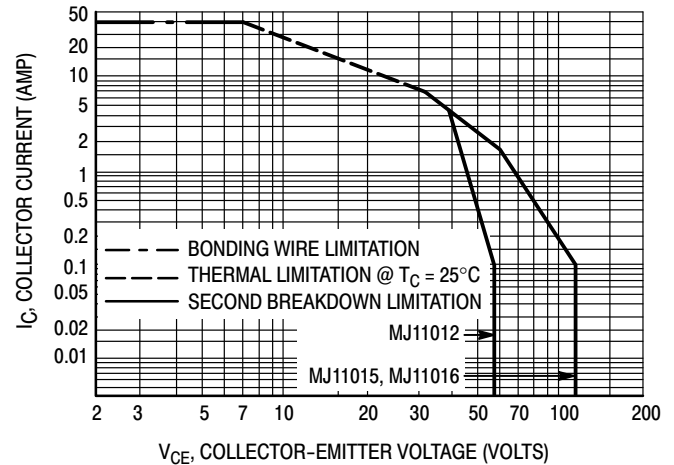


Figure 5. Active Region DC Safe Operating Area

There are two limitations on the power handling ability of a transistor average junction temperature and secondary breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operations e.g., the transistor must not be subjected to greater dissipation than the curves indicate.

At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by secondary breakdown.

